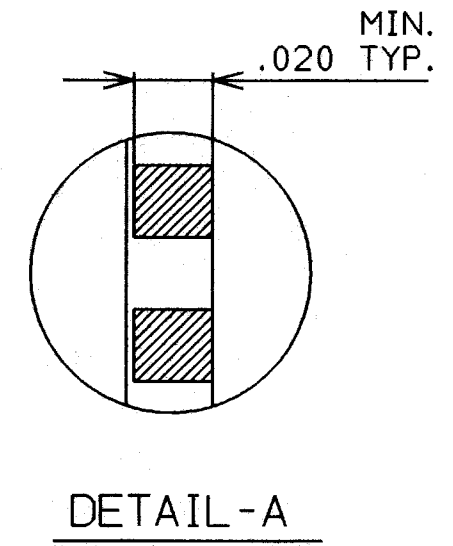
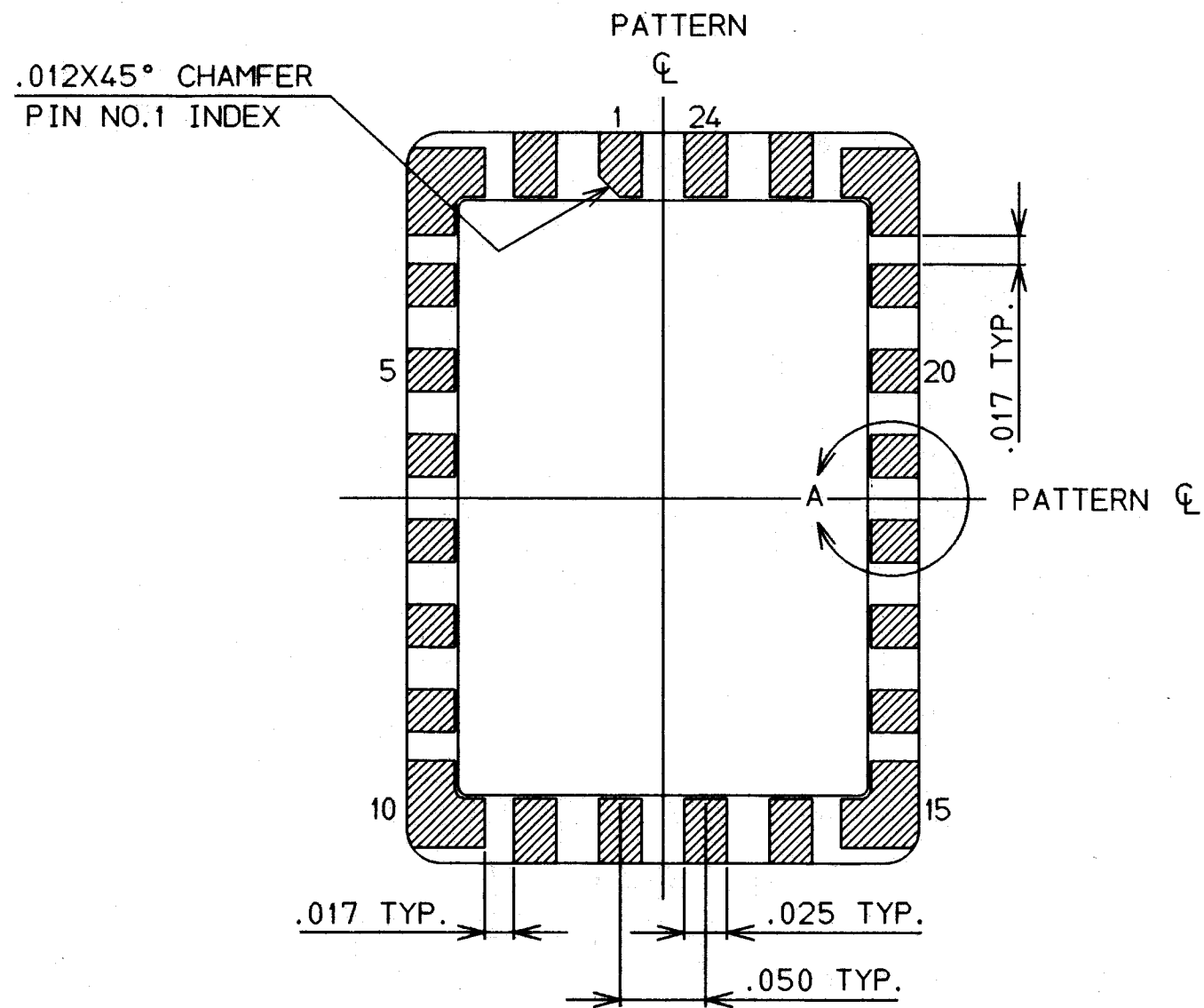


NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.3ΩMAX.

MODIFICATION		NAME	TOLERANCE	DRAWN CHECKED APPROVED DATE	
		24 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	S.S	K.K M.K FEB. 15. '89
		SCALE 5/1	MATERIAL AS INDICATED	THIRD ANGLE PROJECTION	
▲ REDRAWN: (CONVERTED CAD DATA) CHANGED		MAY. 16. '94 S.S.HIT.C/S.FIT.A DATE DRAWN CHECKED APPROVED	±.005 THIRD ANGLE PROJECTION	DRAWING NO. KD-F89139-A SHEET 1/2	
		KYOCERA	KYOCERA CORPORATION KYOTO JAPAN		

FW024W139-1 S=0 B=0	
DRAWN	CHECKED
APPROVED	DATE
S.S	K.K M.K FEB. 15. '89
DRAWING NO. KD-F89139-A	
SHEET 1/2	



BONDING PATTERN

MODIFICATION						NAME	24 LEAD FLAT PACKAGE	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	10 / 1	UNLESS OTHERWISE SPECIFIED	S.S	K.K	M.K	FEB.15.'89
						MATERIAL		THIRD ANGLE PROJECTION				
	▲ REDRAWN: (CONVERTED CAD DATA) CHANGED	MAY.16.'94	S.SH	T.C/S.F	T.A					DRAWING NO.		
	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN			KD-F89139-A			2 / 2